

Patent

OCT 06 2005

Customer No.: 31561
Application No.: 10/709,990
Docket No. 11416-US-PA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Liu et al.
Application No. : 10/709,990
Filed : June 11, 2004
For : SOLDER COMPOSITION
Art Unit : 1742
Examiner : IP, SIKYIN

TRANSMITTAL LETTER

+1-571-273-8300

(Via fax: 1+2+7+2 pages)

ASSISTANT COMMISSIONER FOR PATENTS
Alexandria, VA 22314

Dear Sir,

In response to the Advisory Action dated August 31, 2005, please find the relevant papers as follows:

- ☒ Request for Continued Examination in (2) pages;
- ☒ Preliminary Amendment in (7) pages;
- ☒ Appendix I in (2) pages.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

10/06/2005 HTECKLU1 00000047 502620 10709990

01 FC:1801 790.00 DA

Respectfully Submitted,
JIANQ CHYUN Intellectual Property OfficeDate: Oct. 6, 2005By: Belinda Lee
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